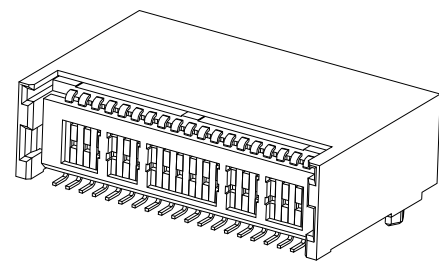
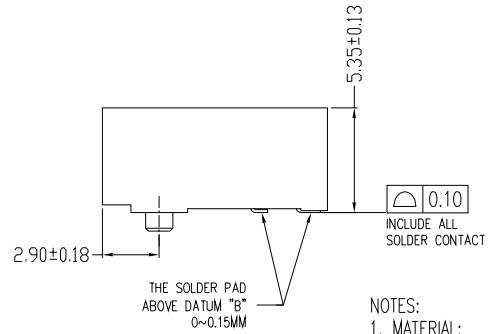
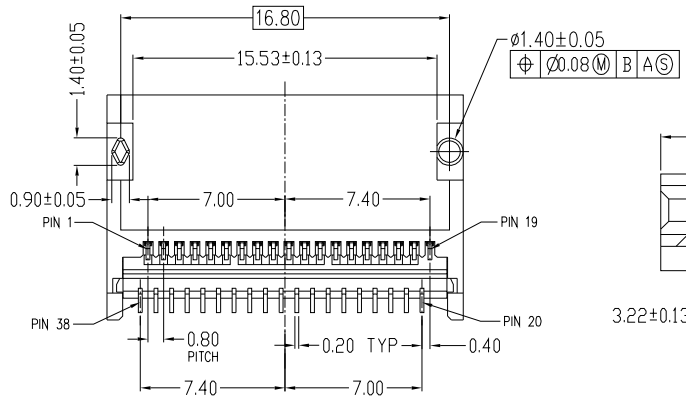
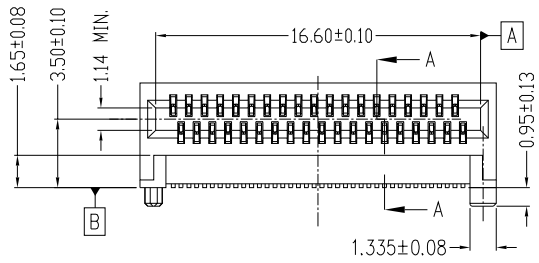
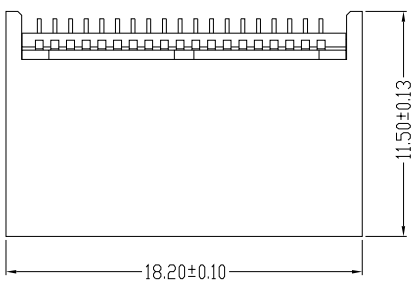
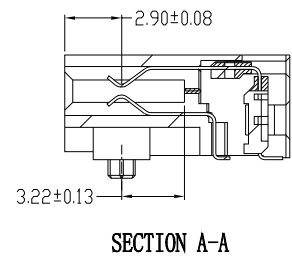


Product Number	Contact Area Plated
10132344-101LF	0.38um Au
10132344-102LF	0.76um Au



- NOTES:
- MATERIAL:  
HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0, BLACK  
TERMINAL : NICKEL COPPER ALLOY
  - PLATING SPEC AS BELOW:  
OPTION 1  
CONTACT AREA PLATE NICKEL 2.54um MIN, PLATE Gold 0.38um MIN  
SOLDER AREA PLATE NICKEL 2.54um MIN, PLATE MATTE TIN 2.54~5.09um  
OPTION 2  
CONTACT AREA PLATE NICKEL 2.54um MIN, PLATE Gold 0.76um MIN  
SOLDER AREA PLATE NICKEL 2.54um MIN, PLATE MATTE TIN 2.54~5.09um
  - ELECTRICAL CHARACTERISTICS  
CONTACT CURRENT RATING: 0.5 AMPERE  
VOLTAGE RATING: 30VAC  
CONTACT RESISTANCE: 40 MILLOHMS MAX  
DIELECTRIC WITHSTANDING VOLTAGE: 300VDC
  - ENVIRONMENT  
OPERATION TEMPERATURE: -40°C TO 85°C
  - PRODUCT SPECIFICATION: GS-12-622
  - PACKAGE PER GS-14-920 AND GS-14-1400
  - APPLICATION SPECIFICATION: GS-20-126

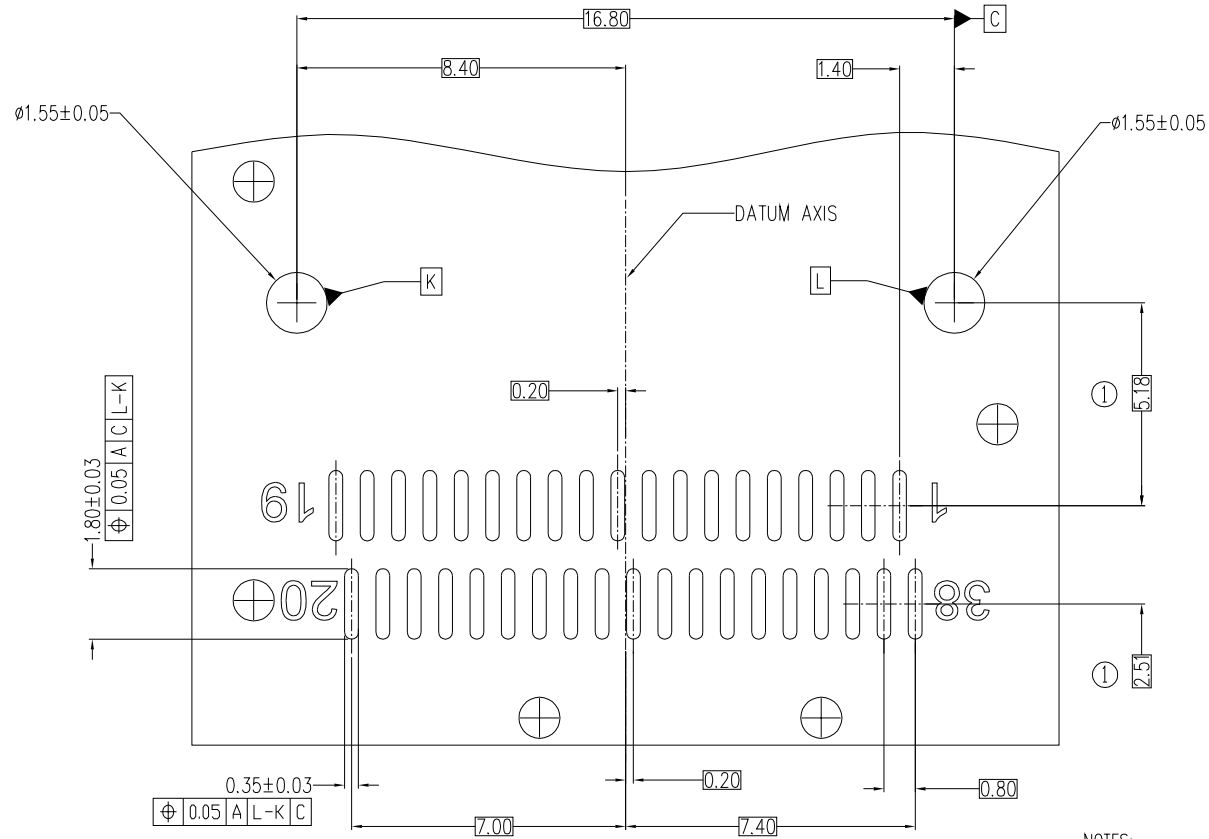


Copyright FCI.

spec ref	RELEASE	dr	Art Lin	2014-12-15	projection	size	scale
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Art Lin	2014-12-15		A4	1:1
ISO406		chr	-	-		ecn no	
ISO1101		appr	Collins Lu	2014-12-16	product family	QSFP+	rel level
surface		linear	0.X	±0.15		10132344	rev
ISO1302		0.XX	±0.05				
	angular	0°	±0.5°		www.fci.com	cat. no.	-

Pro/E File - REV C - 2009-06-09

# MOTHERBOARD FOOTPRINT RECOMMENDATION



Scale 2:1

NOTES:  
 1. DIMENSION TO CENTERLINE OF PAD  
 2. DATUM A IS THE TOP SURFACE OF THE HOST BOARD

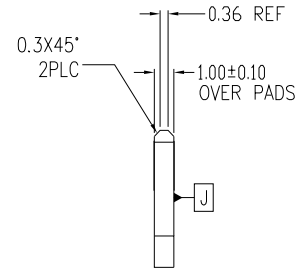
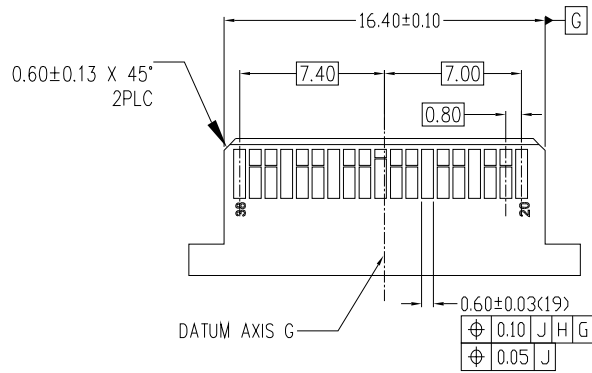


Copyright FCI.

spec ref	RELEASE			dr	Art Lin	2014-12-15	projection	MM	size	A4	scale	1:1	
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Art Lin	2014-12-15			ecn no				
ISO406				chr	-	-			rel level	Released			
ISO1101				appr	Collins Lu	2014-12-16	product family		QSFPP+				
surface		linear	0.X	±0.15		title QSFPP+ Connector 38 Pins SMT Type	dwg no 10132344	rev A					
ISO1302			0.XX	±0.05					www.fci.com	cat. no.	-	Product-Customer Drw	sheet 2 of 3
		angular	0°	±0.5°									

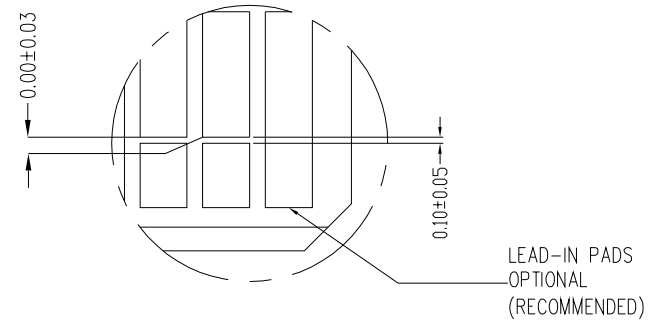
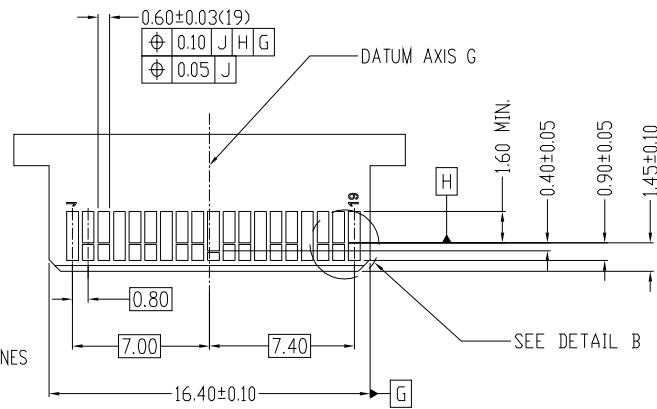
Pro/E File - REV C - 2009-06-09

# MODULE BOARD FOOTPRINT RECOMMENDATION



### NOTES:

- CONTACT PAD PLATING:  
0.38 MICROMETERS MIN GOLD OVER  
1.27 MICROMETERS MIN NICKEL
- NO SOLDER MASK WITHIN 0.05MM OF  
DEFINED PAD LOCATIONS
- ALTERNATE CONTACT PAD PLATING  
0.03 MICROMETERS MIN GOLD OVER  
0.30 MICROMETERS MIN PALLADIUM OVER  
1.27 MICROMETERS MIN NICKEL



**DETAIL B**  
Scale 4:1

DATUM H TARGETS ARE DEFINED  
BY THE RESPECTIVE PAD CENTERLINES  
AND THE LEADING EDGE OF THE  
TARGET PADS

spec ref	RELEASE	dr	Art Lin	2014-12-15	projection	size	scale	
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Art Lin	2014-12-15		A4	1:1	
ISO406		chr	-	-		ecn no		
ISO1101		appr	Collins Lu	2014-12-16	product family	QSFP+	rel level	Released
surface	<input checked="" type="checkbox"/> linear  <input type="checkbox"/> angular	0.X	±0.15		title QSFP+ Connector 38 Pins SMT Type	dwg no 10132344	rev A	
ISO1302		0.XX	±0.05					
	0.XXX	±						
		0°	±0.5°	www.fci.com	cat. no.	-	Product-Customer Drw	sheet 3 of 3

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